## Declaration for U.S. Patent Application

Decial ation for 0.5. I atent Application					
As a below named	d inventor, I hereby declare the	at:			
My residence, pos	st office address and citizensh	ip are as stated below ne	xt to my name.		
names are listed b (Insert Title) SY	elow) of the subject matter wh	hich is claimed and for weather the control of the	sted below) or an original, first and which a patent is sought on the invent RAND PROGRAM THEREFOR cked	ition entitled	
			cation Number or PCT International (if applicable).	Application Number	
	I have reviewed and understa mendment referred to above.	nd the contents of the ab	pove-identified specification, include	ing the claim(s), as	
I acknowledge the § 1.56.	e duty to disclose information	which is material to pate	entability as defined in Title 37, Cod	e of Federal Regulations,	
inventor's certifica		identified below any for	de, § 119 (a) - (d) of any foreign appeign application for patent or invent		
		_		Priority Claimed	
(List prior foreign applications. See note A on back of this page)	2002-275073 (Number)	<u>Japan</u> (Country)	20 September 2002 (Day/Month/Year Filed)	<u>X</u> Yes No	
	(Number)	(Country)	(Day/Month/Year Filed)	Yes No	
	<u> </u>			Yes No	
	(Number)	(Country)	(Day/Month/Year Filed)	Yes No	
	(Number)	(Country)	(Day/Month/Year Filed)		
(See note B on ba	ck of this page)	See attached list for add	litional prior foreign applications		
subject matter of c the first paragraph as defined in Title	each of the claims of this appli of Title 35, United States Code	ication is not disclosed in e, § 112, I acknowledge t ons, § 1.56 which becan	ny United States application(s) listenthe prior United States application the duty to disclose information which available between the filing date of	in the manner provided by h is material to patentability	
(List Prior U.S. Applications)	(Appln. Serial No.)	(Filing Date)	(Status: Patented, Pending, Al	andoned)	
ripplications				<u> </u>	
	(Appln. Serial No.)	(Filing Date)	(Status: Patented, Pending, Al	oandoned)	
	(Appln. Serial No.)	(Filing Date)	(Status: Patented, Pending, Ab	oandoned)	

I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:



Please direct all communications to the following address:



PATENT TRADEMARK OFFICE

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Title 18 of the United States Code, § 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

(See note C	Full name of sole or first inventor (given name, family name)				
above)	Inventor's signature 金分哲哉 Date August 4, 2003				
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Full name of second	inventor (given name, family name)				
Inventor's signature	ventor's signature Date				
Residence	Citizenship				
Post Office Address					
Full name of third in	ventor (given name, family name)				
Inventor's signature	Date				
Residence	Citizenship				
Post Office Address					
Full name of fourth i	nventor (given name, family name)				
	Date				
Residence	Citizenship				
Post Office Address					
Full name of fifth inv	ventor (given name, family name)				
	Date				
-	Citizenship				
Dost Office Address					